

ABSTRACT OF THE DISCLOSURE (FIG. 2)

"POLYPHENYLENE SULFIDE RESIN COMPOSITION AND RESIN-
ENCAPSULATED SEMICONDUCTOR DEVICE"

5 A polyphenylene sulfide resin composition, which
comprises, in addition to a polyphenylene sulfide resin
and an inorganic filler, at least one whisker selected
from the group consisting of titania whisker and
aluminum borate whisker. A resin-encapsulated semicon-
10 ductor device comprising a semiconductor element, and a
resin layer sealing the semiconductor element, wherein
the resin layer is formed of a cured material of the
resin composition.